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Mary-Ann Maher Jung-Chih Chiao Paul J. Resnick Editors

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Contents

- v Conference Committee
- vii The high versatility of silicon based micro-optical modulators (Plenary Paper) [7208-101] H. Schenk, Fraunhofer Institute for Photonic Microsystems (Germany)

SESSION 1 DEVICES

- 7204 02 **Cost-effective method of manufacturing a 3D MEMS optical switch** [7204-01] E. Carr, P. Zhang, D. Keebaugh, K. Chau, Glimmerglass Networks (United States)
- 7204 03 Uncooled infrared and terahertz detectors based on micromechanical mirror as a radiation pressure sensor [7204-02]
 G. P. Berman, B. M. Chernobrod, A. R. Bishop, Los Alamos National Lab. (United States);
 V. N. Gorshkov, Los Alamos National Lab. (United States) and Institute of Physics (Ukraine)
- 7204 04 A novel fabrication method for semiconductor ring lasers that ensures optimal electrical pumping [7204-04]

N. Dutta, J. P. Gupta, J. A. Murakowski, D. W. Prather, Univ. of Delaware (United States)

- 7204 05 Optical fiber packaging for MEMS interfacing [7204-05]
 J. Mireles, Jr., M. A. Garcia, R. C. Ambrosio, Univ. Autónoma de Ciudad Juárez (Mexico);
 E. J. Garcia, Sandia National Labs. (United States); W. Calleja, C. Reyes, Instituto Nacional de Astrofísica, Óptica y Electrónica (Mexico)
- 7204 06 A high sensitivity hall sensor fabricated on a SOI wafer using surface micromachining technique [7204-06] N. Singh, H. V. Estrada, Univ. of North Carolina at Charlotte (United States)
- 7204 07 Sharpened transparent micronozzle fabrication for cell membrane piercing [7204-07]
 E. M. Campo, M. J. Lopez-Martinez, Ctr. Nacional de Microelectrónica (Spain);
 E. Fernández, E. Ibañez, L. Barros, C. Nogues, Univ. Autònoma de Barcelona (Spain);
 J. Esteve, J. A. Plaza, Ctr. Nacional de Microelectrónica (Spain)

SESSION 2 PROCESS: LASERS, MILLING, CMP

- 7204 09 Stretchable multilayer self-aligned interconnects fabricated using excimer laser photoablation and *in situ* masking (Invited Paper) [7204-09] K. L. Lin, K. Jain, Univ. of Illinois at Urbana-Champaign (United States)
- 7204 0A **Pulsed laser breaking technique for glass substrates** [7204-11] C.-H. Tsai, W.-H. Chang, Huafan Univ. (Taiwan)
- 7204 0C **Two-photon polymerization for fabrication of three-dimensional micro- and nanostructures over a large area** [7204-13] M. Malinauskas, V. Purlys, M. Rutkauskas, R. Gadonas, Vilnius Univ. (Lithuania)

7204 0D A study of the influence of cutting parameters on micromilling of steel with cubic boron nitride (CBN) tools [7204-14] F. Klocke, F. Quito, K. Arntz, A. Souza, Fraunhofer Institute for Production Technology (Germany)

SESSION 3 SPECIAL SESSION ON CAD

7204 0J **1/f noise in single-walled carbon nanotube films** [7204-21] A. Behnam, G. Bosman, A. Ural, Univ. of Florida (United States)

POSTER SESSION

- 7204 0N **Polymeric nanosieves fabricated by UV lithography** [7204-26] L. Gutierrez-Rivera, L. Cescato, Univ. of Campinas (Brazil)
- Nanorod measurement-layer separate structure for nanorod-character measurement, simulation, and application as sensor devices [7204-29]
 M.-K. Leem, J.-U. Park, C.-M. Kim, K.-J. Kim, S.-H. Yeom, W.-Y. Choi, Kyungpook National Univ. (Korea, Republic of); W.-S. Kang, J.-H. Kim, Ajou Univ. (Korea, Republic of); S.-W. Kang, Kyungpook National Univ. (Korea, Republic of)

Author Index

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